

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Jong-Soo CHOI, et al.
Serial No.: 10/748,868 Examiner: Nguyen, Hoa Cao
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Title: PRINTED CIRCUIT BOARD WHICH CAN BE CONNECTED WITH
PIN CONNECTOR AND METHOD OF MANUFACTURING THE
PRINTED CIRCUIT BOARD

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Responsive to the Office Action, Paper No. 02012006, dated February 7, 2006, please amend the application as follows.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 5 of this paper.

IN THE SPECIFICATION

Applicants request that the following paragraphs in the specification be amended as follows:

1) Please replace the paragraph starting on page 3, line 11 with:

FIG. 5 is a view of a printed circuit board before a solder screen printing process is performed. In general, the printed circuit board includes a printed circuit unit 200 and a tap unit 210. Pads are formed on the printed circuit unit 200 so that chips or other electrical components can be mounted on the printed circuit unit 200. The pads are electrically connected to one another. The tap unit 210 is electrically connected with the printed circuit unit 200 and with an external pin connector. In FIG. 5, solder has not been yet formed on the pads and the tap unit 210. In addition, FIG. 5 shows a first side of ~~both sides~~ the printed circuit board to which a surface mount technology (SMT) is applied.

2) Please replace the paragraph starting on page 3, line 19 with:

Referring to FIGS. 4 and 5, ~~in a case of the~~ when both sides of a printed circuit board ~~which is manufactured by SMT, first, undergo a SMT application,~~ a solder screen printing is applied to the tap unit 210 of the first side (step 100). Step 100 can be performed when solder screen printing is applied to surfaces of pads on the first side of the printed circuit unit 200. By applying solder screen printing to the tap unit 210 in step 100 while applying solder screen printing to surfaces of the pads, an additional process is not required to apply solder screen printing to the tap unit 210 of the first side.